

(C) WPI/Derwent

AN - 1988-312248 [44]

A - [001] 014 02& 06- 07& 074 075 077 081 09& 130 133 135 137 15- 18- 199
220 221 226 229 231 239 26& 266 267 303 305 306 307 308 310 314 330
331 336 341 353 364 365 392 394 395 397 40- 400 44& 473 477 48- 506
509 532 536 54& 541 548 549 575 58- 583 589 597 600 623 627 656 659
681 720 721 723

AP - JP19870066683 19870319

CPY - TOYM

DC - A82 G02 V04

DR - 1278-U 1541-U 1966-U 5067-U 5085-U 5196-U 5222-U 5388-U

FS - CPI;EPI

IC - C08F2/48 ; C08F4/00 ; H05K3/28

KS - 0036 0037 0060 0072 0205 0224 0226 0506 0590 1176 1239 1373 1601 2016
2020 2021 2208 2209 2210 2211 2218 2285 2293 2300 2303 2307 2315 2321
2333 2502 2551 2572 2585 2600 2608 2609 2718 2737 2792 2812 3183 3204
3252

MC - A08-C01 A08-M01D A10-E07B A11-C02B G02-A02B G02-A04A G02-A05 G02-A05B
- V04-R03 V04-R04A2

PA - (TOYM) TOYOBO KK

PN - JP63230705 A 19880927 DW198844 007pp

PR - JP19870066683 19870319

XA - C1988-138173

XIC - C08F-002/48 ; C08F-004/00 ; H05K-003/28

XP - N1988-236821

AB - J63230705 Compsns. contain (1) photopolymerisable prepolymers, (2)
photopolymerisable monomers, (3) photopolymerisation initiators, (4)
heat polymerisation initiators and (5) epoxy gp.-contg. silane
couplers.

- Pref. (1) has a mol.wt. of 500-5000. Blend wt. ratio of (1):(2) is
95:5-10:90, pref. 80:20-15:85 The total of (1) and (2) constitutes
20-80 wt.% of the compsn. The amts. of (3), (4) and (5) used are
0.1-10 wt.%, 0.01-10 wt.% and 0.01-10 wt.%, respectively, of the
compsn. Opt. the resin compsns. are blended with 1-60 (10-50) wt.% of
inorganic fillers e.g. CaCO₃, talc, 1-15 wt.% of organic or inorganic
pigments e.g. TiO₂, carbon black, heat polymerisation inhibitors, or
surface-smoothing agents.

- USE/ADVANTAGE - The compsns. are used as binders for solder resist
ink, insulating paste, overlay ink, marking ink, as coating agent and
paints. The solder resist ink has a high soldering heat resistance as
above 270 deg.C, high moisture resistance (120 deg.C/2 atmos.
pressure), good adhesive property, solvent resistance and storage
stability.(0/0)

IW - ULTRAVIOLET CURE RESIN COMPOSITION COMPRISE PHOTOPOLYMERISE
PREPOLYMER

PHOTOPOLYMERISE MONOMER PHOTO HEAT POLYMERISE INITIATE

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PREPOLYMER

PHOTOPOLYMERISE MONOMER PHOTO HEAT POLYMERISE INITIATE

NC - 001

OPD - 1987-03-19

ORD - 1988-09-27

PAW - (TOYM) TOYOBO KK

TI - UV curable resin compsn. - comprises photopolymerisable prepolymers,
photopolymerisable monomer(s), photo- and heat polymerisation
initiators etc.